

Abstract of the Disclosure

A solid-state image pickup apparatus having over solid-state image pickup device chip a hermetic seal portion comprising a flat-plate portion of a transparent member and a frame portion formed on a side portion of a lower surface of the flat-plate portion, said frame portion including a metal wiring, a bump formed on said solid-state image pickup device chip and electrically connected to the metal wiring, and a sealing region for sealing the periphery of the bump by a sealing material, thereby achieving the solid-state image pickup apparatus capable of being packaged in a relatively small size and capable of improving throughput and at the same time having a hermetic seal portion which can be readily electrically connected to an external terminal.